

Since 1980

# FLIP CHIP BONDER-S100



FLIP CHIP BONDER - S100



## High Productivity

- 15,000 UPH (Based on Dry Run)



## High Reliability

- One Casting Body Structure



## Precision Bonding Capability

- $\pm 15\mu\text{m } 3\sigma$



## Low Cost of Ownership

- Economic Version of Flip Chip Bonder



Semiconductor

# FLIP CHIP BONDER S100

## Enhanced Machine Features

### High Productivity

- 15,000 UPH (Based on Dry Run)
- Dual Bonding Head
- Hanmi Special Sequence Profile
- Enhanced Temperature Control System



### User Friendly & Easy Operation

- Windows Based HMI Screen
- Easy & Quick Conversion
- Easy Maintenance



Die Chipout Inspection



Eject Cup F/M



Wafer Ejector Pin Maker Inspection

## Components and Substrates

Wafer	Die Size	0.5 x 0.5mm ~ 10 x 10mm
	Die Thickness	0.1mm ~ 3.0mm
	Wafer Size	up to 12"
Substrate	Width	28mm ~ 208mm
	Length	50mm ~ 300mm

## Performance

Productivity	UPH	15,000 (Based on Dry Run)	MTBA	2~5 hours
Accuracy	X-Y Placement	$\pm 15\mu\text{m } 3\sigma$		
	Chip Rotation ( $\theta$ )	$\pm 0.1^\circ @ 3\sigma$	MTBF	168 hours
Bonding Head	Bonding Force	1N ~ 20N (Programmable from 1N)	MTTA	3 minutes
Footprint	Dimension (W x D x H)	1,600mm x 1,200mm x 1,500mm	MTTR	30 minutes
	Weight	2,700 kg		